IN THE SPECIFICATION:

Please replace paragraph number **[0001]** with the following rewritten paragraph:

[0001] This application is a divisional of application Serial No. 09/617,692, filed July 17, 2000, ~~pending~~ now U.S. Patent 6,666,751, issued December 23, 2003.

Please replace paragraph number **[0069]** with the following rewritten paragraph:

[0069] The size and shape of the solid supports included in a deformable pad of the present invention may also be varied in ~~order~~ order to alter or optimize the physical properties of the deformable pad. For example, as shown in FIG. 17, which schematically illustrates top views of various differently shaped solid supports, the solid supports of a deformable pad of the present invention may be multifaceted (i.e., pyramidal 218a and 218b, rectangular 218c, pentagonal 218d, hexagonal 218e, heptagonal 218f, octagonal 218g, or cylindrical 218h, etc.), or the solid supports may include flanges 219 or cutouts 220, as can be seen in solid supports 218i and 218j, respectively. In addition, FIG. 18 shows that the solid supports included in a deformable pad according to the present invention may be conical 218k or parabolic 218l in shape, or the solid supports may be fabricated with a tapered waste, as can be seen in solid support 218m, a tapered bottom section, as can be seen in solid support 218n, or tapered top and bottom sections, as shown in solid support 218o. As can be further appreciated from reference to FIG. 19, the solid supports included in a deformable pad of the present invention may be formed using irregular shapes, such as solid supports ~~218 p~~ 218p, particularly where such irregular shapes enhance desired qualities of the deformable pad of the present invention. Finally, adjusting the height or width of each solid support will also result in solid supports of varying resiliency and durability. For example, a taller, thinner solid support will likely result in a solid support that is less resistant to shearing and compressive forces than a shorter, wider solid support made of the same material. Thus, the solid supports of the deformable pad of the present invention are exceedingly variable, and by varying the size or shape of the solid supports, deformable pads of varying resiliency and durability can be achieved.

Please replace paragraph number **[0072]** with the following rewritten paragraph:

[0072] The present invention also includes a polishing apparatus useful in CMP, which incorporates a deformable pad of the present invention. The polishing apparatus of the present invention may further include known machinery used to carry out CMP processes. For example, FIG. 12 illustrates an exemplary polishing apparatus 130 according to the present invention which incorporates a deformable pad 108 according to the fourth embodiment of the deformable pad of the present invention and includes a polishing platen, or table 132, having an upper surface 134 and driven by a mechanical assembly 136 well-known in the art, such as an electric motor. A deformable pad 108 according to the present invention is directly or indirectly attached to the upper surface 134 of the polishing table 132 by any suitable means, such as those already discussed. However, the upper surface 134 of the polishing table 132 may be covered by an additional layer of material 133, such as a protective SUBA IV layer produced by ~~RODEL®~~ RODEL®. As has been detailed, where an additional layer of material 133 is included on the upper surface 134 of a polishing table 132, the deformable pad 108 is indirectly adhered to or attached to the upper surface 134 of the polishing table 132 by attaching the deformable pad 108 to the upper surface 137 of the additional layer of material 133.

Please replace paragraph number **[0073]** with the following rewritten paragraph:

[0073] The exemplary polishing apparatus 130 illustrated in FIG. 12 also includes a polishing pad 142, as is known in the art, attached to the deformable pad 108 of the present invention. The polishing pad 142 may be any suitable polishing pad known in the art, such as a ~~RODEL®~~ RODEL® IC1000 polishing pad, and, as has been previously disclosed, the polishing pad 142 may be attached to the deformable pad 108 by well-known means. Further, the polishing apparatus 130 may include a rotatable substrate carrier 138 which holds the semiconductor substrate 140 in place as the polishing pad 142 or the substrate carrier 138 rotates or otherwise agitates. The substrate carrier 138 of the polishing apparatus 130 may hold the semiconductor substrate 140 in place using well-known techniques. The substrate carrier 138 may be rotatable and may also provide agitation through movement in a plane (indicated by

arrow 143) parallel to the upper surface 134 of the polishing table 132. The substrate carrier 138 may also be driven by any one of several known mechanical assemblies 144 known in the art. Additionally, the substrate carrier 138 is designed to exert a downward force (indicated by arrow 146) on the semiconductor substrate 140 substantially normal to the surface 148 of the material layer 150 of the semiconductor substrate 140 being polished, thereby generating a pressure between the surface 148 being polished and the polishing surface 151 of the polishing pad 142.